

Please replace the paragraph beginning at page 4, line 18, with the following rewritten paragraph:

A2  
--The solder bumps 3 are located on the connecting pad of the semiconductor element 1 and the connecting pad of the wiring board 2. Flux is not supplied to the solder bumps 3, located on the semiconductor element 1 and the wiring board 2, according to Embodiment 1. An ultrasonic bonding head 4 sucks the semiconductor element 1 by vacuum and can apply an ultrasonic wave while heating the semiconductor element 1 from a room temperature to 400°C. In a bonding stage 5, a heater is built-in to previously heat the wiring board 2 to a temperature around a fusing point of solder.--

Please replace the paragraph beginning at page 5, line 3, with the following rewritten paragraph:

A3  
--As illustrated in Figure 1a, the wiring board 2 is registered and mounted on an upper surface of the bonding stage 5, heated to around the fusing point of solder. On the other hand, the semiconductor element 1 is sucked on a lower surface of the ultrasonic bonding head 4, heated to less than the fusing point of solder. The semiconductor element 1 is positioned above the wiring board 2 so as to be aligned by a horizontal movement of the ultrasonic bonding head 4.--

Please replace the paragraph beginning at page 5, line 12, with the following rewritten paragraph:

A4  
--As illustrated in Figure 1b, the ultrasonic bonding head 4 is moved downward, and the semiconductor element 1 is mounted at a predetermined position on the wiring board 2. Under this state, since the semiconductor element is sucked on the lower surface of the ultrasonic bonding head 4, the semiconductor element is in contact with the wiring board 2